

Power Semiconductor Market Report by Component (Discrete, Module, Power Integrated Circuits), Material (Silicon/Germanium, Silicon Carbide (SiC), Gallium Nitride (GaN)), End Use Industry (Automotive, Consumer Electronics, Industrial, Power and Energy, IT and Telecommunication, Military and Aerospace, and Others), and Region 2024-2032

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Abstracts

The global power semiconductor market size reached US\$ 43.1 Billion in 2023. Looking forward, IMARC Group expects the market to reach US\$ 58.7 Billion by 2032, exhibiting a growth rate (CAGR) of 3.4% during 2024-2032.

Power semiconductors are fundamental components of modern power electronic circuitry machines that convert energy from one form to another at various stages. They are manufactured using silicon carbide (Sic), germanium and gallium nitride (GaN). These devices are widely being used for wireless communication, motion control, computer systems, advanced control of electric drives, antennas, broadband wireless techniques and satellite systems. Power semiconductors form an indispensable part of electrical appliances, machines, and systems and are majorly used in applications requiring conversion of large voltages and currents without damages. As compared to electro-mechanical converter systems, power semiconductors offer a faster dynamic response, lower installation cost and reduced thermal dissipation. Consequently, they are widely used across various industries, such as automotive, military, aerospace, consumer electronics, information technology and telecommunications.

Power Semiconductor Market Trends:

Rapid expansion in the automotive industry across the globe is one of the key factors



creating a positive outlook for the market growth. Power semiconductors are widely fitted with electronic components and integrated chips in automobile parts, such as steering systems, braking, fuel delivery and safety systems. In line with this, the widespread product adoption in electric vehicles, plug-in electric vehicles, and hybrid electric vehicles (EVs/HEVs) for providing higher efficiency in converters and enhancing battery management systems and power electronic switches are favoring the market growth. Moreover, various technological advancements, such as the utilization of x-by-wire or drive-by-wire technologies that assist in decreasing the weight of the vehicle, enhancing fuel efficiency and reducing emission, are providing an impetus to the market growth. Additionally, the widespread product utilization in lightweight, small and portable consumer electronics, such as smartphones, tablets, smartwatches, fitness bands and communication devices, is positively impacting the market growth. Other factors, including increasing demand for renewable energy sources and the implementation of various government initiatives to promote power-efficient devices, are anticipated to drive the market further.

Key Market Segmentation:

IMARC Group provides an analysis of the key trends in each sub-segment of the global power semiconductor market report, along with forecasts at the global, regional and country level from 2024-2032. Our report has categorized the market based on component, material and end use industry.

Breakup by Component:

Discrete Module Power Integrated Circuits

Breakup by Material:

Silicon/Germanium Silicon Carbide (SiC) Gallium Nitride (GaN)

Breakup by End Use Industry:

Automotive Consumer Electronics Industrial



Power and Energy IT and Telecommunication Military and Aerospace Others

Breakup by Region:

North America **United States** Canada Asia-Pacific China Japan India South Korea Australia Indonesia Others Europe Germany France United Kingdom Italy Spain Russia Others Latin America Brazil Mexico Others Middle East and Africa

Competitive Landscape:

The competitive landscape of the industry has also been examined along with the profiles of the key players being ABB Ltd., Broadcom Inc., Fuji Electric Co. Ltd., Hitachi Ltd., Infineon Technologies AG, Microchip Technology Inc., Mitsubishi Electric Corporation, NXP Semiconductor Inc., Onsemi, Renesas Electronics Corporation, ROHM Co. Ltd., STMicroelectronics, Texas Instruments Incorporated, Toshiba Corporation and Vishay Intertechnology Inc.



Key Questions Answered in This Report: How has the global power semiconductor market performed so far and how will it perform in the coming years? What has been the impact of COVID-19 on the global power semiconductor market? What are the key regional markets? What is the breakup of the market based on the component? What is the breakup of the market based on the material? What is the breakup of the market based on the end use industry? What are the various stages in the value chain of the industry? What are the key driving factors and challenges in the industry? What is the structure of the global power semiconductor market and who are the key players? What is the degree of competition in the industry?



Contents

1 PREFACE

2 SCOPE AND METHODOLOGY

- 2.1 Objectives of the Study
- 2.2 Stakeholders
- 2.3 Data Sources
- 2.3.1 Primary Sources
- 2.3.2 Secondary Sources
- 2.4 Market Estimation
- 2.4.1 Bottom-Up Approach
- 2.4.2 Top-Down Approach
- 2.5 Forecasting Methodology

3 EXECUTIVE SUMMARY

4 INTRODUCTION

- 4.1 Overview
- 4.2 Key Industry Trends

5 GLOBAL POWER SEMICONDUCTOR MARKET

- 5.1 Market Overview
- 5.2 Market Performance
- 5.3 Impact of COVID-19
- 5.4 Market Forecast

6 MARKET BREAKUP BY COMPONENT

- 6.1 Discrete
- 6.1.1 Market Trends
- 6.1.2 Market Forecast
- 6.2 Module
 - 6.2.1 Market Trends
 - 6.2.2 Market Forecast
- 6.3 Power Integrated Circuits



6.3.1 Market Trends 6.3.2 Market Forecast

7 MARKET BREAKUP BY MATERIAL

7.1 Silicon/Germanium
7.1.1 Market Trends
7.1.2 Market Forecast
7.2 Silicon Carbide (SiC)
7.2.1 Market Trends
7.2.2 Market Forecast
7.3 Gallium Nitride (GaN)
7.3.1 Market Trends
7.3.2 Market Forecast

8 MARKET BREAKUP BY END USE INDUSTRY

- 8.1 Automotive
 - 8.1.1 Market Trends
- 8.1.2 Market Forecast
- 8.2 Consumer Electronics
 - 8.2.1 Market Trends
 - 8.2.2 Market Forecast
- 8.3 Industrial
 - 8.3.1 Market Trends
- 8.3.2 Market Forecast
- 8.4 Power and Energy
 - 8.4.1 Market Trends
 - 8.4.2 Market Forecast
- 8.5 IT and Telecommunication
- 8.5.1 Market Trends
- 8.5.2 Market Forecast
- 8.6 Military and Aerospace
 - 8.6.1 Market Trends
 - 8.6.2 Market Forecast
- 8.7 Others
 - 8.7.1 Market Trends
 - 8.7.2 Market Forecast



9 MARKET BREAKUP BY REGION

9.1 North America 9.1.1 United States 9.1.1.1 Market Trends 9.1.1.2 Market Forecast 9.1.2 Canada 9.1.2.1 Market Trends 9.1.2.2 Market Forecast 9.2 Asia-Pacific 9.2.1 China 9.2.1.1 Market Trends 9.2.1.2 Market Forecast 9.2.2 Japan 9.2.2.1 Market Trends 9.2.2.2 Market Forecast 9.2.3 India 9.2.3.1 Market Trends 9.2.3.2 Market Forecast 9.2.4 South Korea 9.2.4.1 Market Trends 9.2.4.2 Market Forecast 9.2.5 Australia 9.2.5.1 Market Trends 9.2.5.2 Market Forecast 9.2.6 Indonesia 9.2.6.1 Market Trends 9.2.6.2 Market Forecast 9.2.7 Others 9.2.7.1 Market Trends 9.2.7.2 Market Forecast 9.3 Europe 9.3.1 Germany 9.3.1.1 Market Trends 9.3.1.2 Market Forecast 9.3.2 France 9.3.2.1 Market Trends 9.3.2.2 Market Forecast 9.3.3 United Kingdom



9.3.3.1 Market Trends 9.3.3.2 Market Forecast 9.3.4 Italy 9.3.4.1 Market Trends 9.3.4.2 Market Forecast 9.3.5 Spain 9.3.5.1 Market Trends 9.3.5.2 Market Forecast 9.3.6 Russia 9.3.6.1 Market Trends 9.3.6.2 Market Forecast 9.3.7 Others 9.3.7.1 Market Trends 9.3.7.2 Market Forecast 9.4 Latin America 9.4.1 Brazil 9.4.1.1 Market Trends 9.4.1.2 Market Forecast 9.4.2 Mexico 9.4.2.1 Market Trends 9.4.2.2 Market Forecast 9.4.3 Others 9.4.3.1 Market Trends 9.4.3.2 Market Forecast 9.5 Middle East and Africa 9.5.1 Market Trends 9.5.2 Market Breakup by Country 9.5.3 Market Forecast

10 SWOT ANALYSIS

10.1 Overview10.2 Strengths10.3 Weaknesses10.4 Opportunities10.5 Threats

11 VALUE CHAIN ANALYSIS



12 PORTERS FIVE FORCES ANALYSIS

- 12.1 Overview
- 12.2 Bargaining Power of Buyers
- 12.3 Bargaining Power of Suppliers
- 12.4 Degree of Competition
- 12.5 Threat of New Entrants
- 12.6 Threat of Substitutes

13 PRICE ANALYSIS

14 COMPETITIVE LANDSCAPE

14.1 Market Structure 14.2 Key Players 14.3 Profiles of Key Players 14.3.1 ABB Ltd. 14.3.1.1 Company Overview 14.3.1.2 Product Portfolio 14.3.1.3 Financials 14.3.1.4 SWOT Analysis 14.3.2 Broadcom Inc. 14.3.2.1 Company Overview 14.3.2.2 Product Portfolio 14.3.2.3 Financials 14.3.2.4 SWOT Analysis 14.3.3 Fuji Electric Co. Ltd. 14.3.3.1 Company Overview 14.3.3.2 Product Portfolio 14.3.3.3 Financials 14.3.3.4 SWOT Analysis 14.3.4 Hitachi Ltd. 14.3.4.1 Company Overview 14.3.4.2 Product Portfolio 14.3.4.3 Financials 14.3.4.4 SWOT Analysis 14.3.5 Infineon Technologies AG 14.3.5.1 Company Overview 14.3.5.2 Product Portfolio



- 14.3.5.3 Financials
- 14.3.5.4 SWOT Analysis
- 14.3.6 Microchip Technology Inc.
- 14.3.6.1 Company Overview
- 14.3.6.2 Product Portfolio
- 14.3.6.3 Financials
- 14.3.6.4 SWOT Analysis
- 14.3.7 Mitsubishi Electric Corporation
 - 14.3.7.1 Company Overview
 - 14.3.7.2 Product Portfolio
- 14.3.7.3 Financials
- 14.3.7.4 SWOT Analysis
- 14.3.8 NXP Semiconductor Inc.
- 14.3.8.1 Company Overview
- 14.3.8.2 Product Portfolio
- 14.3.8.3 Financials
- 14.3.8.4 SWOT Analysis
- 14.3.9 Onsemi
- 14.3.9.1 Company Overview
- 14.3.9.2 Product Portfolio
- 14.3.9.3 Financials
- 14.3.9.4 SWOT Analysis
- 14.3.10 Renesas Electronics Corporation
- 14.3.10.1 Company Overview
- 14.3.10.2 Product Portfolio
- 14.3.10.3 Financials
- 14.3.10.4 SWOT Analysis
- 14.3.11 ROHM Co. Ltd.
- 14.3.11.1 Company Overview
- 14.3.11.2 Product Portfolio
- 14.3.11.3 Financials
- 14.3.11.4 SWOT Analysis
- 14.3.12 STMicroelectronics
- 14.3.12.1 Company Overview
- 14.3.12.2 Product Portfolio
- 14.3.13 Texas Instruments Incorporated
- 14.3.13.1 Company Overview
- 14.3.13.2 Product Portfolio
- 14.3.13.3 Financials



- 14.3.13.4 SWOT Analysis
- 14.3.14 Toshiba Corporation
- 14.3.14.1 Company Overview
- 14.3.14.2 Product Portfolio
- 14.3.14.3 Financials
- 14.3.14.4 SWOT Analysis
- 14.3.15 Vishay Intertechnology Inc.
 - 14.3.15.1 Company Overview
 - 14.3.15.2 Product Portfolio
 - 14.3.15.3 Financials
 - 14.3.15.4 SWOT Analysis



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